

20V P-Channel MOSFET

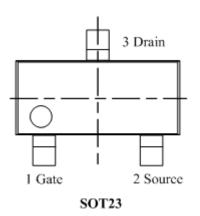
General Description

The BF92301P uses advanced trench technology to provide excellent $R_{DS(ON)}$ and low gate charge. This device is suitable for used as a load switch or in PWM applications.

Features

- V_{DS} (V) = -20V
- I_D = -2.8A
- Low on-state resistance

$$R_{DS (on)}$$
 = 80m Ω TYP. (V_{GS} = -4.5V)
 $R_{DS (on)}$ =100m Ω TYP.(V_{GS} = -2.5V)

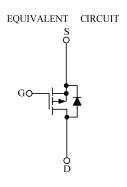


Absolute Maximum Ratings (Ta = 25℃)

| Parameter | Symbol | Value | Unit | | | | | |
|--|-----------------------|----------|---------------|--|--|--|--|--|
| P-MOSFET | | | | | | | | |
| Drain to Source Voltage | V_{DSS} | -20 | V | | | | | |
| Gate to Source Voltage | V_{GSS} | ±8 | V | | | | | |
| Drain Current (DC) | I _{D(DC)} | -2.8 | Α | | | | | |
| Drain Current (pulse) ^a | I _{D(pulse)} | -8 | Α | | | | | |
| Maximun Power Dissipation ^a | P_{D} | 1.3 | W | | | | | |
| Channel Temperature | T_ch | 150 | $^{\circ}$ | | | | | |
| Storage Temperature | T _{stg} | -55~+150 | ${\mathbb C}$ | | | | | |

Note: Mounted on FR4 Board of 1"x1".

Caution: These values must not be exceeded under any conditions.



P-Channel MOSFET

Ordering Information

Part Number : BF92301PPackage : SOT-23



Electrical Characteristics ($T_A = 25^{\circ}C$)

| Symbol | Characteristics | Test Conditions | Min. | Тур. | Max. | Unit |
|----------------------|-------------------------------------|--|-------|-------|-------|------|
| I _{DSS} | Zero Gate Voltage Drain Current | V _{DS} = -20V,V _{GS} =0V | | | -1 | μA |
| I _{GSS} | Gate Leakage Current | V _{GS} =±8V,V _{DS} =0V | | | ±100 | nA |
| V _{GS} (th) | Gate threshold voltage | $V_{DS}=V_{GS}$, $I_D=250\mu A$ | -0.45 | | -0.95 | V |
| y _{fs} | Forward Transfer Admittance | V _{DS} = -5V,I _D = -4A | | 6.5 | | S |
| R _{DS(on)} | Drain to Source On-state Resistance | V _{GS} = -4.5V,I _D = -1.4A | | 80 | 100 | mΩ |
| | | V _{GS} = -2.5V,I _D = -1.4A | | 100 | 150 | mΩ |
| Ciss | Input Capacitance | V _{GS} =0V, V _{DS} =-15V,f=1.0MHZ | | 386.6 | | pF |
| Coss | Output Capacitance | | | 62.9 | | pF |
| Crss | Reverse Transfer Capacitance | | | | | pF |
| t _{d(on)} | Turn-on Delay Time | V_{DD} =-10V, I_{D} =-1.4A, V_{GS} =-4.5V, R_{G} =4.7 Ω | | 20.7 | | ns |
| t _r | Rise Time | | | 5.6 | | ns |
| t _{d(off)} | Turn-off Delay Time | | | 40.05 | | ns |
| t _f | Fall Time | | | 7.4 | | ns |
| Q_G | Total Gate Charge | V _{DD} =-10V, I _D =-1.4A, | | 6.5 | | nC |
| Q_{GS} | Gate to Source Charge | | | 1.5 | | nC |
| Q_{GD} | Gate to Drain Charge | V_{GS} =-4.5V, R_{G} =10 Ω | | 1.5 | | nC |
| V _{SD} | Drain-Source Diode Forward Voltage | I _s =-2.8A,V _{GS} =0V | | | -1.2 | V |

Typical characteristics (25℃ unless noted)

Figure 1 Output Caracteristics

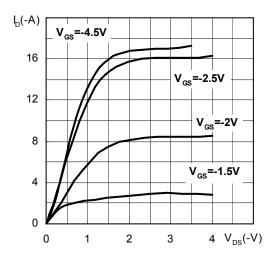


Figure 2 Transfer Characteristics

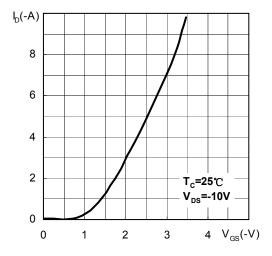


Figure 3 On Resistance VS Temperature

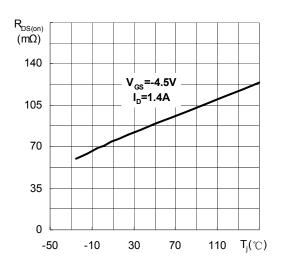


Figure4 Threshold Voltage

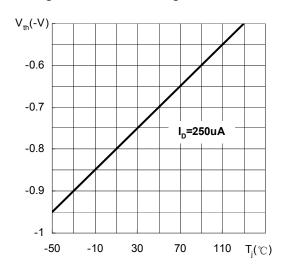


Figure 7 Capacitance

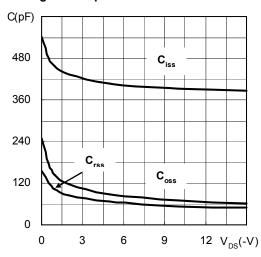


Figure 8 Gate Charge

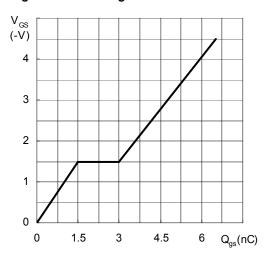
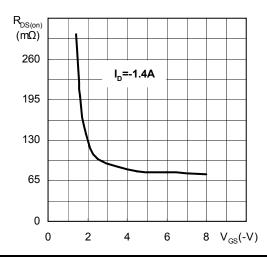
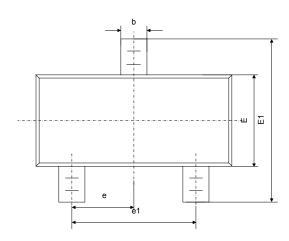
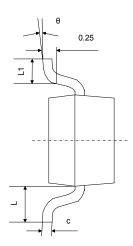


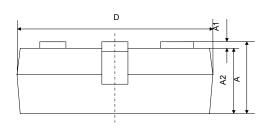
Figure 7 On Resistance VS Gate to Source Voltage



Package Drawing







| Symbol | Dimensions In Millimeters | | Dimensions In Inches | | |
|------------|---------------------------|-------|----------------------|-------|--|
| | Min | Max | Min | Max | |
| Α | 0.009 | 1.150 | 0.035 | 0.045 | |
| A 1 | 0.000 | 0.100 | 0.000 | 0.004 | |
| A2 | 0.900 | 1.050 | 0.035 | 0.041 | |
| b | 0.300 | 0.500 | 0.012 | 0.020 | |
| С | 0.080 | 0.150 | 0.003 | 0.006 | |
| D | 2.800 | 3.000 | 0.110 | 0.118 | |
| E | 1.200 | 1.400 | 0.047 | 0.055 | |
| E1 | 2.250 | 2.550 | 0.089 | 0.100 | |
| е | 0.950TYP | | 0.037TYP | | |
| e1 | 0.800 | 2.000 | 0.071 | 0.079 | |
| L | 0.550REF | | 0.022REF | | |
| L1 | 0.300 | 0.500 | 0.012 | 0.020 | |
| θ | 0° | 8° | 0° | 6° | |

Note:

- 1. Dimension D does not include mold flash, protrusions or gate burrs. mold flash, protrusions or gate burrs shall not exceed 0.10mm per side.
- 2. Dimension E1 does not include inter-lead flash or protrusion. Inter-lead flash or protrusion shall not exceed 0.1mm per side.

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